

Fig. 1a: Embodiment of a Lead Frame Panel

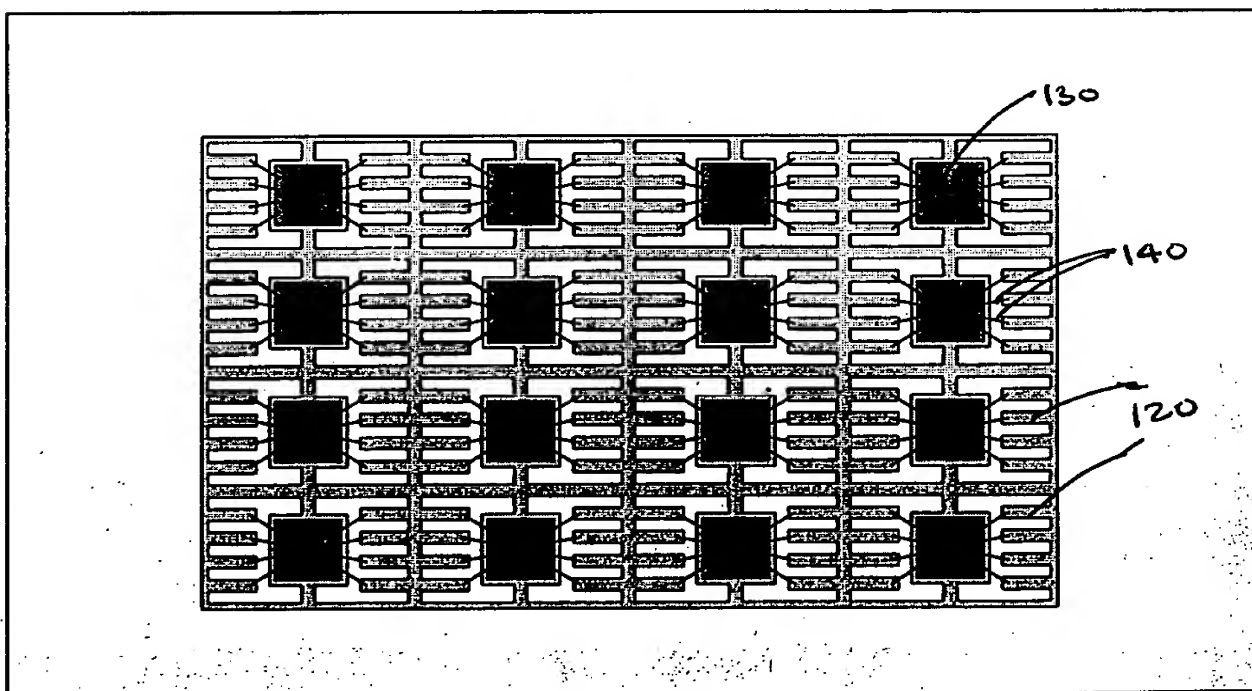


Fig. 1b: Lead Frame with IC Chips Attached

Fig 8

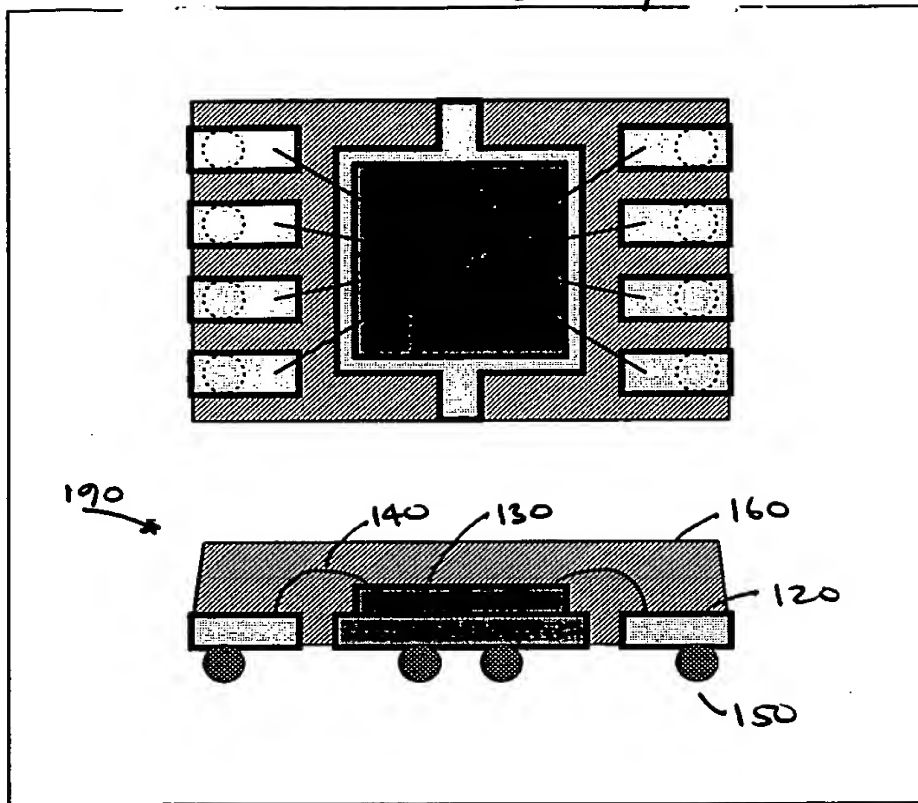


Fig. 1c: Finished BGA IC Package

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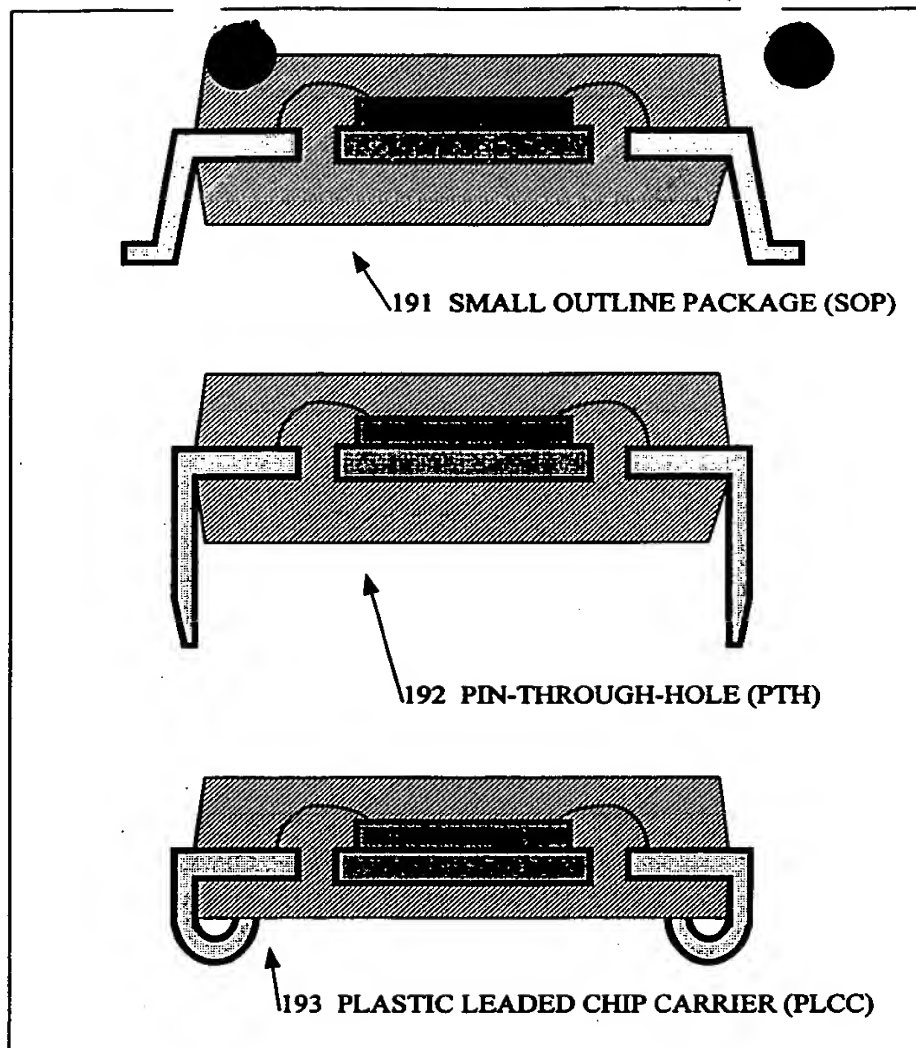


Fig. 1d: Examples of IC Packages

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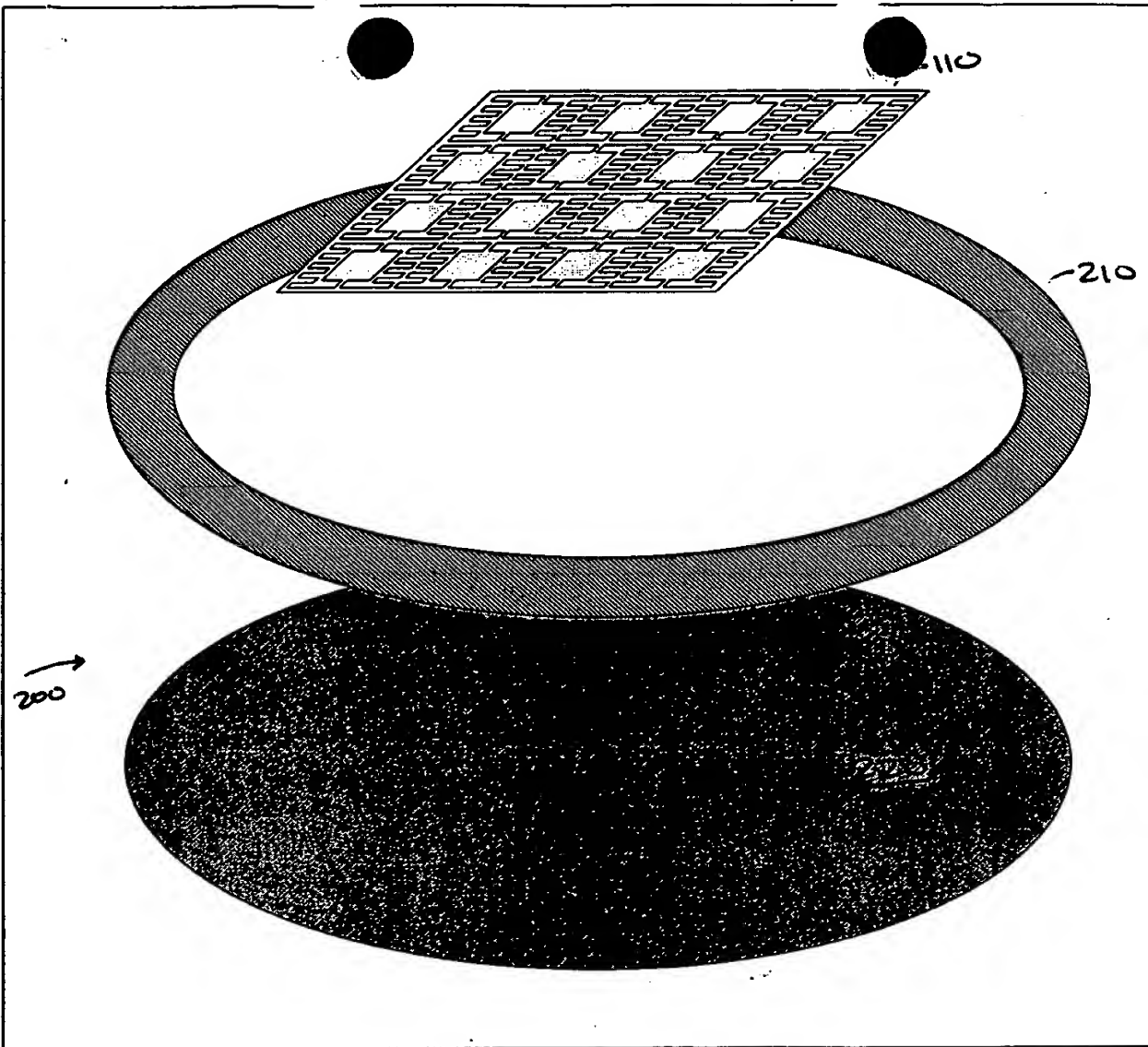


Fig. 2a: Lead Frame Panel Support Structure

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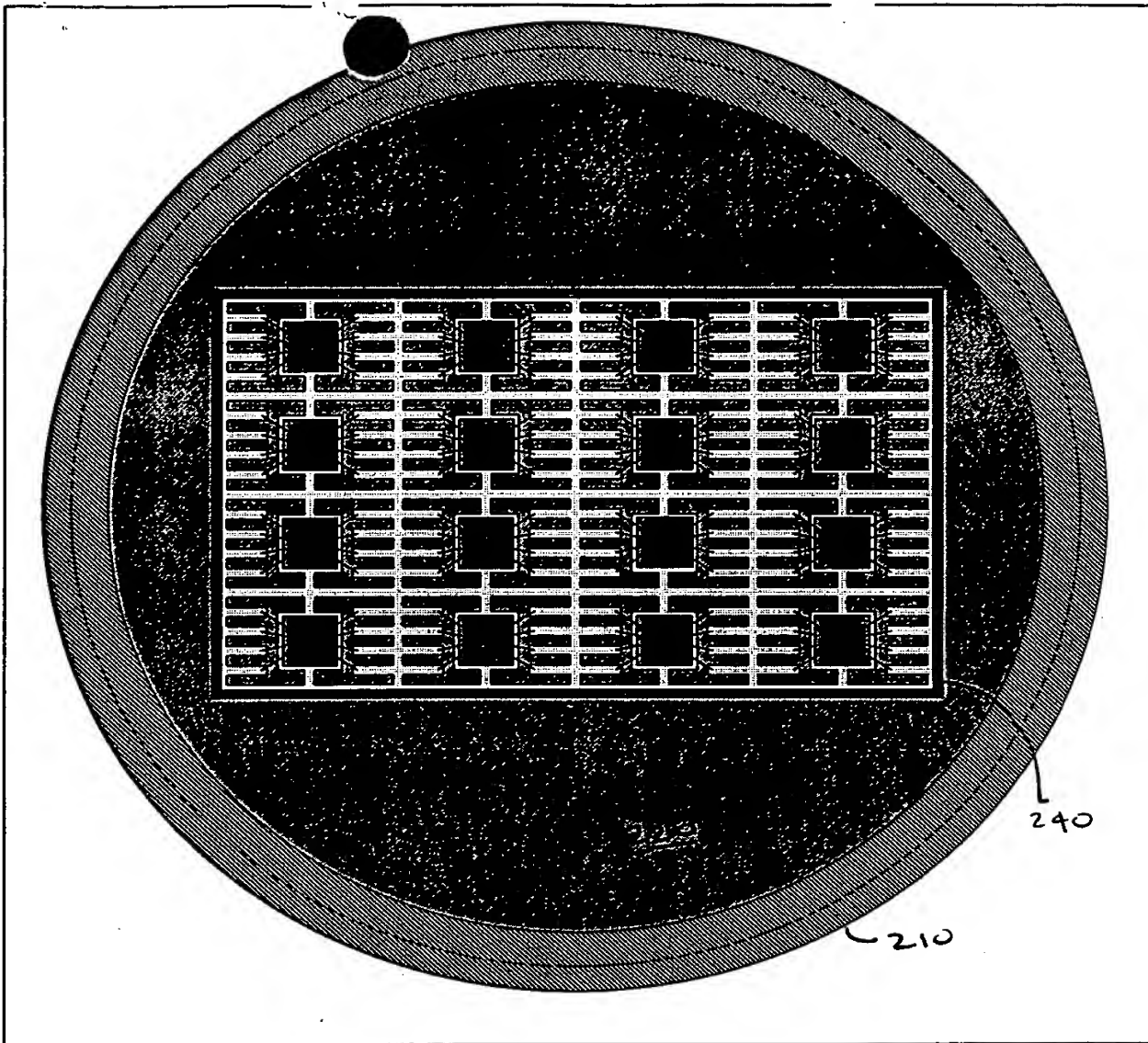
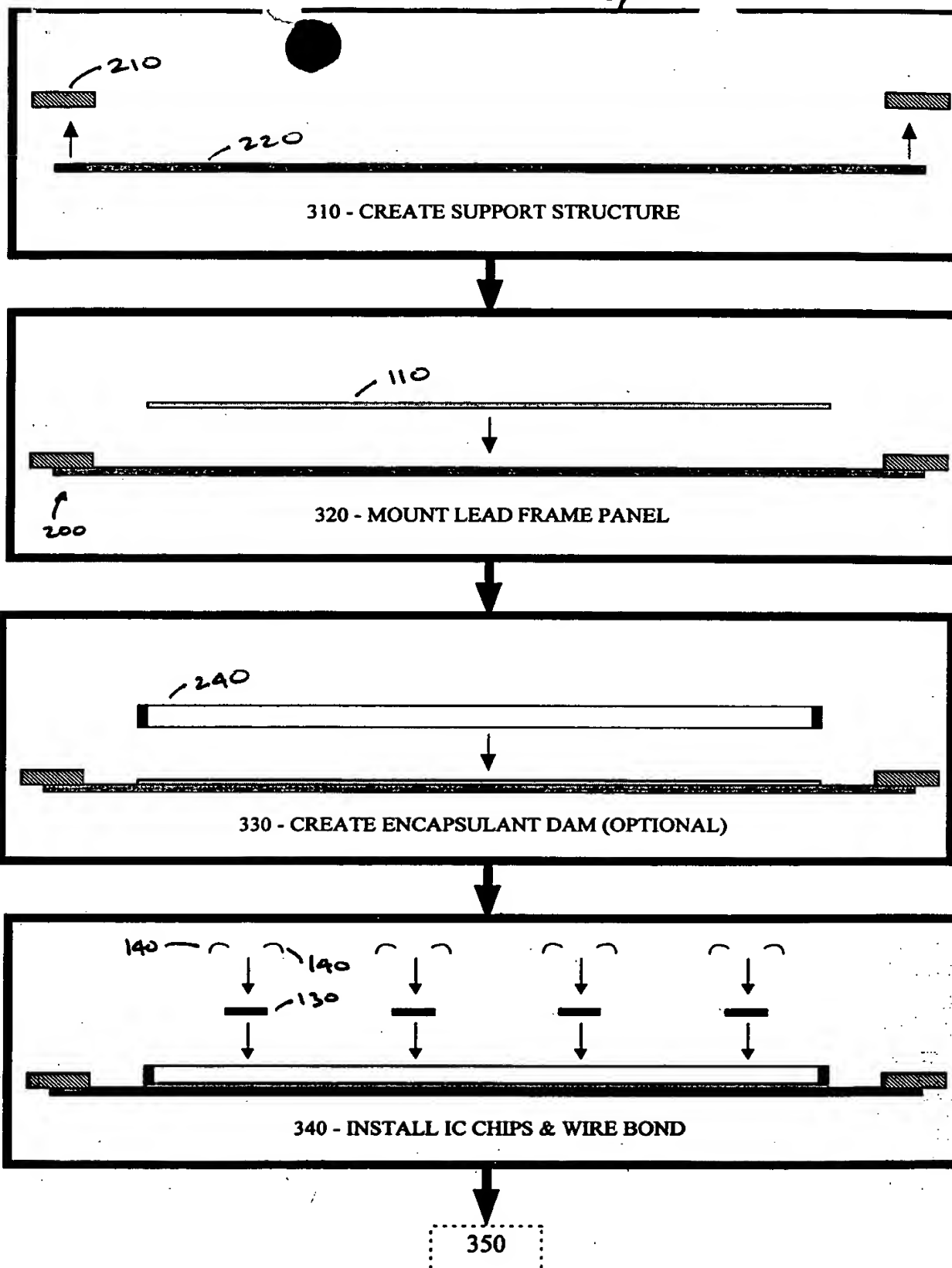


Fig. 2b: Lead Frame Panel Mounted on Support Structure with IC Chips Installed

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Fig. 3a: Flow Chart for Lead Frame BGA Process Using an Embodiment of the Present Invention, Part 1

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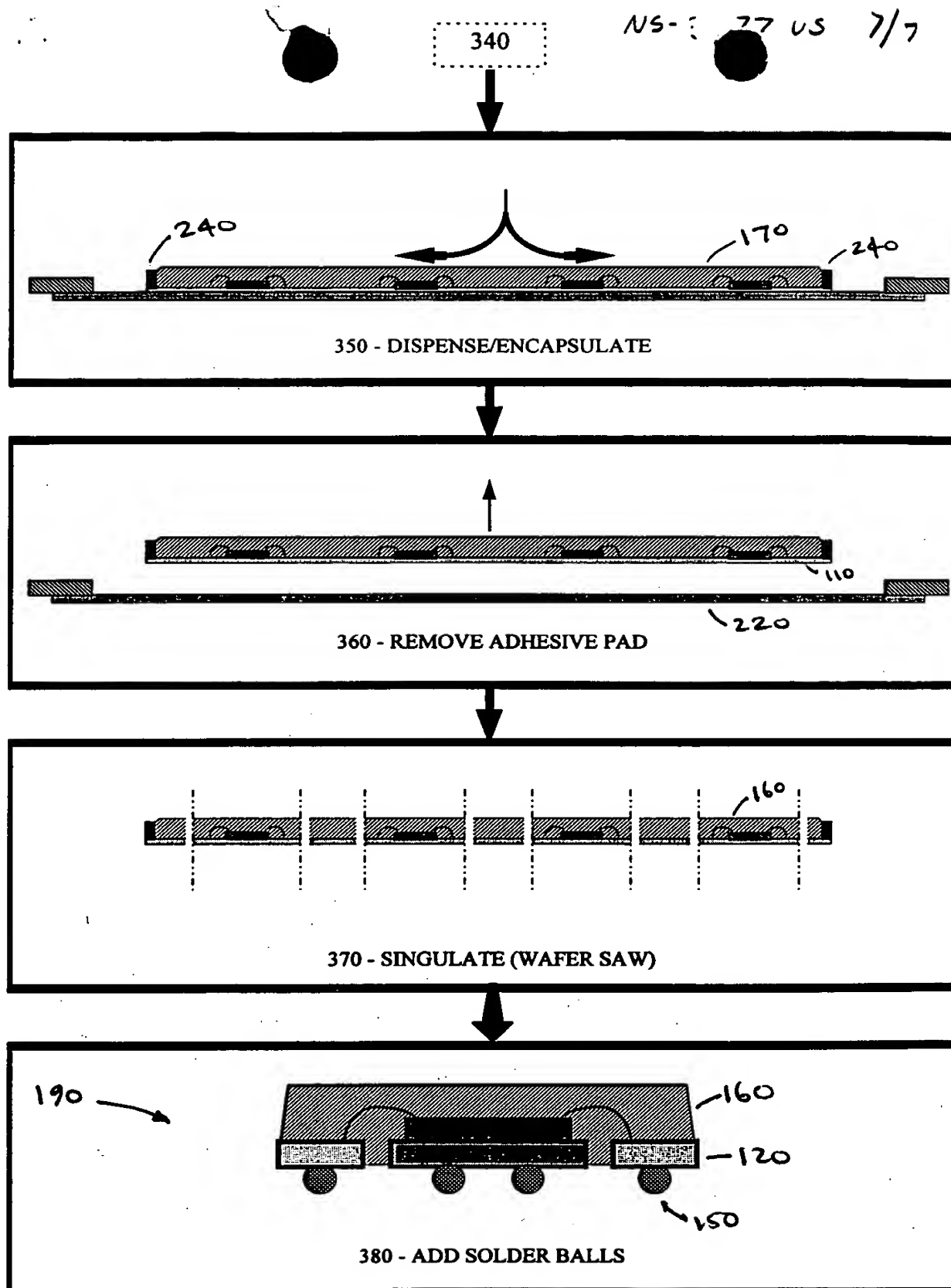


Fig. 3b: Flow Chart for Lead Frame BGA Process Using an Embodiment of the Present Invention, Part 2